

F6810/F68A10/F68B10 128 x 8-Bit Static Random Access Memory

Microprocessor Product

Description

The F6810 128 x 8-bit static RAM is a byte-organized memory designed for use in bus-organized systems. Fabricated with n-channel, silicon-gate technology, the device is available in three frequency ranges: 1.0 MHz (F6810), 1.5 MHz (F68A10), 2.0 MHz (F68B10). The device, which operates from a single power supply, is compatible with TTL and DTL; it needs no clocks or refreshing because of its static operation.

The memory is compatible with the F6800 microcomputer family, providing random storage in byte increments. Memory expansion is provided through multiple chip select inputs.

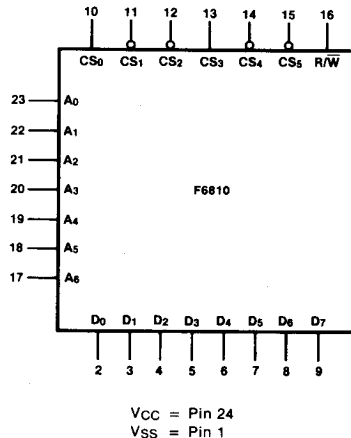
- Organized as 128 Bytes of 8 Bits
- Static Operation
- Bidirectional 3-State Data Input/Output
- Six Chip Select Inputs
(Four Active LOW, Two Active HIGH)
- Single +5 V Power Supply
- TTL-Compatible
- Maximum Access Time:
450 ns for F6810
360 ns for F68A10
250 ns for F68B10

Pin Names

D₀-D₇
A₀-A₆
CS₀-CS₅
R/W

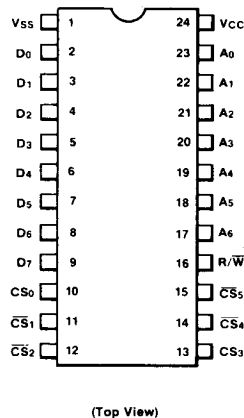
Bidirectional Data Bus
Address Inputs
Chip Select Inputs
Read/Write Input

Logic Symbol

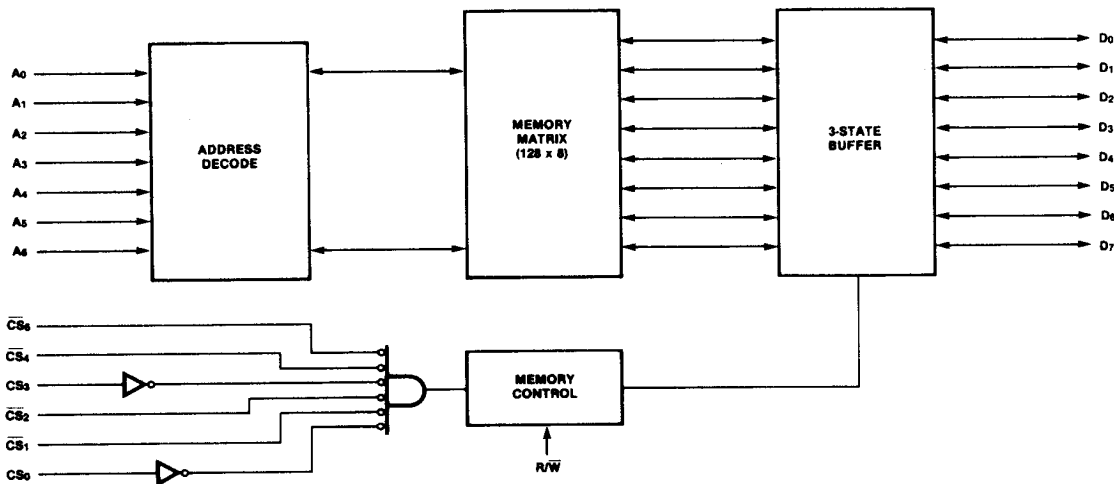


5

**Connection Diagram
24-Pin DIP**



Block Diagram



Signal Function Descriptions

Mnemonic	Pin No.	Name	Description
Bus Handshake			
A ₀ -A ₆	17-23	Address Bus	Input signal lines containing address to which data is to be written or from which data is to be read
D ₀ -D ₇	2-9	Data Bus	Bidirectional input/output signal lines over which data is read from or written to the device
Chip Control			
CS ₀ -CS ₅	10-15	Chip Select	Input signal lines that prepare the device for a read or write operation
R/W	16	Read/Write	Input signal lines that selects a chip read or write operation; a HIGH selects memory read, and a LOW selects memory write
Supply			
V _{SS}	1	Ground	Ground for supply and signals
V _{CC}	24	Supply	+5 V supply voltage

Absolute Maximum Ratings

Supply Voltage	-0.3 V, +7.0 V
Input Voltage	-0.3 V, +7.0 V
Operating Temperature - T _L , T _H	0°C, +70°C
F6810, F68A10, F68B10	-40°C, +85°C
F6810C, F68A10C	-55°C, +125°C
F6810DM	-65°C, +150°C
Storage Temperature Range	-65°C, +150°C
Thermal Resistance - θ _{JA}	82.5°C/W

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages.

These are stress ratings only, and functional operation at these ratings, or under any conditions above those indicated in this data sheet, is not implied. Exposure to the absolute maximum rating conditions for extended periods of time may affect device reliability, and exposure to stresses greater than those listed may cause permanent damage to the device.

Recommended Operating Conditions

Symbol	Characteristic	Min	Typ	Max	Unit
V _{CC}	Supply Voltage	4.75	5.0	5.25	V
V _{IH}	Input HIGH Voltage	2.0		5.25	V
V _{IL}	Input LOW Voltage	-0.3		0.8	V

F6810/F68A10/F68B10

DC Characteristics $V_{CC} = 5.0\text{ V} \pm 5\%$, $V_{SS} = 0$, $T_A = T_L$ to T_H , unless otherwise noted.

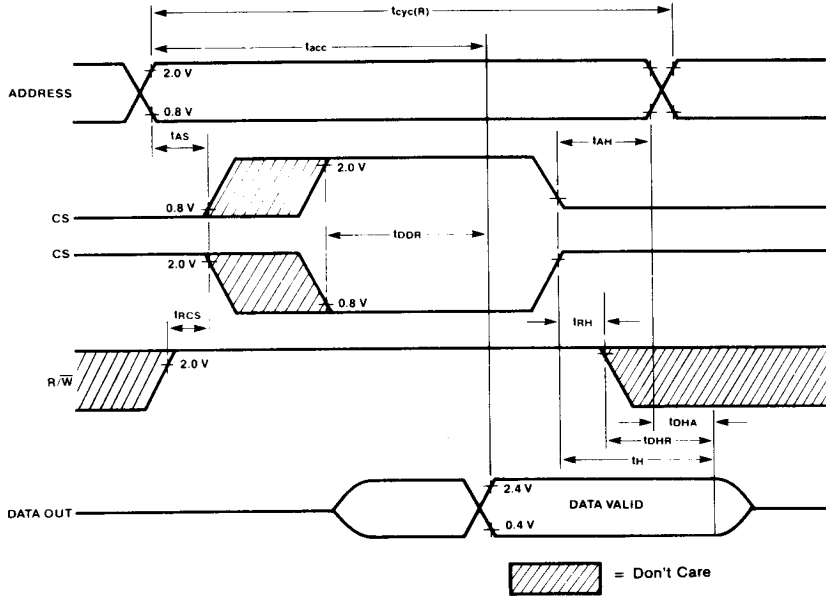
Symbol	Characteristic	Min	Typ	Max	Unit	Conditions
I_{IN}	Input Current (A_n , R/W, CS_n , \overline{CS}_n)			2.5	μA	$V_{IN} = 0$ to 5.25 V
V_{OH}	Output HIGH Voltage	2.4			V	$I_{OH} = -205\ \mu\text{A}$
V_{OL}	Output LOW Voltage			0.4	V	$I_{OL} = 1.6\text{ mA}$
I_{LO}	Output Leakage Current, 3-State			10	μA	$\overline{CS} = 0.8\text{ V}$ or $\overline{CS} = 2.0\text{ V}$, $V_O = 0.4\text{ V}$ to 2.4 V
I_{CC}^*	Supply Current F6810 F68A10, F68B10			80 100	mA	$V_{CC} = 5.25\text{ V}$, all other pins grounded, $T_A = 0^\circ\text{C}$
C_{IN}	Input Capacitance			7.5	pF	$f = 1.0\text{ MHz}$,
C_{OUT}	Output Capacitance			12.5	pF	$T_A = 25^\circ\text{C}$

Bus Timing Characteristics $V_{CC} = 5.0\text{ V} \pm 5\%$, $V_{SS} = 0$, $T_A = T_L$ to T_H , unless otherwise noted.

5

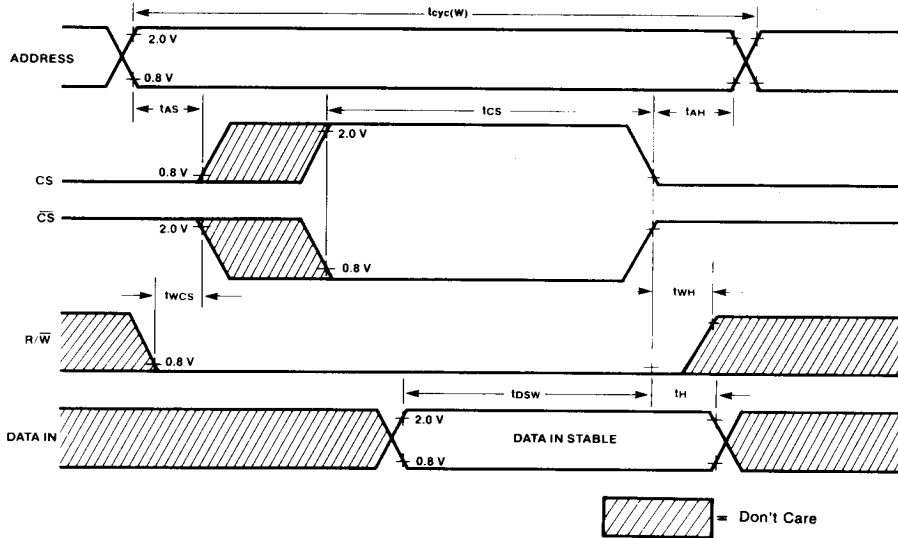
Symbol	Characteristic	F6810		F68A10		F68B10		Unit
		Min	Max	Min	Max	Min	Max	
Read (Figure 1)								
$t_{cyc(R)}$	Read Cycle Time	450		360		250		ns
t_{acc}	Access Time		450		360		250	ns
t_{AS}	Address Set-up Time	20		20		20		ns
t_{AH}	Address Hold Time	0		0		0		ns
t_{DDR}	Data Delay Time (Read)		230		220		180	ns
t_{RCS}	Read-to-Select Delay Time	0		0		0		ns
t_{DHA}	Data Hold from Address	10		10		10		ns
t_H	Output Hold Time	10		10		10		ns
t_{DHR}	Data Hold from Read	10	80	10	60	10	60	ns
t_{RH}	Read Hold from Chip Select	0		0		0		ns
Write (Figure 2)								
$t_{cyc(W)}$	Write Cycle Time	450		360		250		ns
t_{AS}	Address Set-up Time	20		20		20		ns
t_{AH}	Address Hold Time	0		0		0		ns
t_{CS}	Chip Select Pulse Width	300		250		210		ns
t_{WCS}	Write-to-Chip Select Delay Time	0		0		0		ns
t_{DSW}	Data Set-up Time (Write)	190		80		60		ns
t_H	Input Hold Time	10		10		10		ns
t_{WH}	Write Hold from Chip Select	0		0		0		ns

Fig. 1 Read Cycle Timing



Note
 \overline{CS} and \overline{CS} can be enabled for consecutive read cycles, provided R/\overline{W} remains at V_{IH} .

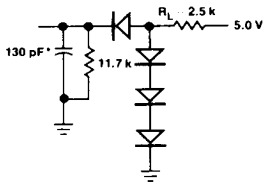
Fig. 2 Write Cycle Timing



5

Note
 CS and CS-bar can be enabled for consecutive write cycles, provided R/W is strobed to V_{IH} before or coincident with the address change, and remains HIGH for time t_{AS}.

Fig. 3 Output Load



*Includes jig capacitance

Timing Conditions

The conditions under which the timing characteristics have been determined are as follows:

Input Pulse Levels	0.8 V to 2.0 V
Input Rise and Fall Times	20 ns
Output Load	See Figure 3
V _{CC}	5.0 V ± 5%
V _{SS}	0
T _A	T _L to T _H , unless otherwise noted

Ordering Information

Speed	Order Code	Temperature Range
1.0 MHz	F6810P,S	0°C to 70°C
	F6810CP,CS	- 40°C to + 85°C
	F6810DM	- 55°C to + 125°C
1.5 MHz	F68A10P,S	0°C to + 70°C
	F68A10CP,CS	- 40°C to + 85°C
2.0 MHz	F68B10DM	- 55°C to + 125°C
	F68B10P,S	0°C to + 70°C

P = Plastic package, S = Ceramic package